

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1 - 2. (canceled).

Claim 3. (new): A circuit, comprising:

a substrate;

a first conducting track on the substrate;

a second conducting track on the substrate, wherein the second conducting track is spaced from the first conducting track so as to form an opening between the first conducting track and the second conducting track;

an electrical component bridging the opening, the electrical component comprising:

an electrical part;

a first conducting part; and

a second conducting part;

wherein the first conducting part is electrically coupled to the first conducting track and the second conducting part is electrically coupled to the second conducting track; and

wherein the first conducting track extends beyond the first conducting part to a position under the electrical part.

Claim 4. (new): The circuit according to claim 3, wherein the electrical part is between the first conducting part and the second conducting part.

Claim 5. (new): The circuit according to claim 3, wherein the circuit is a printed circuit board.

Claim 6. (new): The circuit according to claim 5, wherein the first and second conducting tracks are printed on the substrate.

Claim 7. (new): The circuit according to claim 3, further comprising an adhesive on the first conducting track, the adhesive adhering the electrical component to the first conducting track.

Claim 8. (new): The circuit according to claim 7, wherein the adhesive directly adheres the electrical part of the electrical component to the first conducting track.

Claim 9. (new): The circuit according to claim 3, wherein the electrical part includes circuitry between the first conducting part and the second conducting part, the first and second conducting parts being electrical leads to the circuitry.

Claim 10. (new): The circuit according to claim 3, wherein the first and second conducting tracks are copper or aluminum.

Claim 11. (new): The circuit according to claim 3, wherein a thickness of the first conducting track is greater than 105 microns.

Claim 12. (new): The circuit according to claim 3, wherein an inner edge of the second conducting track facing the opening is substantially aligned with the inner edge of the second conducting part of the electrical component, which also faces the opening.

Claim 13. (new): The circuit according to claim 3, wherein a distance, a_1 , from an outer edge of the first conducting part to an inner edge of the first conducting part, where the first conducting part meets the electrical part of the electrical component, is less than a distance, a_2 , from the outer edge of the first conducting part to an inner edge of the first conducting track facing the opening.

Claim 14. (new): A circuit, comprising:

a substrate;

a first conducting track on the substrate;

a second conducting track on the substrate, wherein the second conducting track is spaced from the first conducting track so as to form an opening between the first conducting track and the second conducting track;

an electrical component bridging the opening, the electrical component comprising:

an electrical part;

a first conducting part; and

a second conducting part;

wherein the first conducting part is electrically coupled to the first conducting track and the second conducting part is electrically coupled to the second conducting track; and

an adhesive on the first conducting track, the adhesive adhering the electrical component to the first conducting track.

Claim 15. (new): The circuit according to claim 14, wherein the electrical part is between the first conducting part and the second conducting part.

Claim 16. (new): The circuit according to claim 14, wherein the circuit is a printed circuit board.

Claim 17. (new): The circuit according to claim 16, wherein the first and second conducting tracks are printed on the substrate.

Claim 18. (new): The circuit according to claim 14, wherein the electrical part includes circuitry between the first conducting part and the second conducting part, the first and second conducting parts being electrical leads to the circuitry.

Claim 19. (new): The circuit according to claim 14, wherein a thickness of the first conducting track is greater than 105 microns.

Claim 20. (new): The circuit according to claim 3, wherein a distance, a_1 , from an outer edge of the first conducting part to an inner edge of the first conducting part, where the first conducting part meets the electrical part of the electrical component, is less than a distance, a_2 , from the outer edge of the first conducting part to an inner edge of the first conducting track facing the opening.

Claim 21. (new): A circuit, comprising:

a substrate;

a first conducting track on the substrate;

a second conducting track on the substrate, wherein the second conducting track is spaced from the first conducting track so as to form an opening between the first conducting track and the second conducting track;

an electrical component bridging the opening, the electrical component comprising:

an electrical part;

a first conducting part; and

a second conducting part;

wherein the first conducting part is electrically coupled to the first conducting track and the second conducting part is electrically coupled to the second conducting track; and

wherein the first conducting track comprises a pad extending from a side of the first conducting track facing the opening and an adhesive on the pad, the adhesive adhering the electrical component to the first conducting track.

Claim 22. (new): The circuit according to claim 21, wherein the pad extends under the electrical part.